

P-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)		
- 60	$0.020 \text{ at V}_{GS} = -10 \text{ V}$	- 50		
	0.025 at V _{GS} = - 4.5 V	- 45		

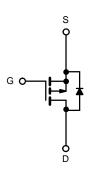
FEATURES

- TrenchFET® Power MOSFET
- Material categorization:



APPLICATIONS

Load Switch



P-Channel MOSFET

TO-252					
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G	D	∐ S			
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ABSOLUTE MAXIMUM RATINGS (T	$_{A}$ = 25 °C, unless othe	rwise noted)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V_{DS}	- 60	V		
Gate-Source Voltage	V _{GS}	± 20] v		
Continuous Drain Current (T _{.1} = 175 °C)	T _C = 25 °C	I-	- 50	A	
Continuous Diain Current (1) = 173 C)	T _C = 125 °C	I _D	- 40		
Pulsed Drain Current	I _{DM}	- 160			
Avalanche Current	I _{AS}	- 50			
Single Pulse Avalanche Energy ^a	L = 0.1 mH	E _{AS}	125	mJ	
Power Discinction	T _C = 25 °C	P _D	113 ^c	W	
Power Dissipation	T _A = 25 °C	' D	2.5 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Junction-to-Ambient ^b	t ≤ 10 s	R _{thJA}	15	18	°C/W	
Junction-to-Ambient	Steady State		40	50		
Junction-to-Case		R_{thJC}	0.82	1.1		

Notes:

- a. Duty cycle \leq 1 %.
- b. When mounted on 1" square PCB (FR-4 material).
- c. See SOA curve for voltage derating.
- d. Package limited.



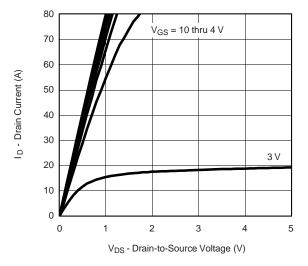
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.5		- 3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = - 60 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μΑ	
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 150 °C			- 100		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 50			Α	
		V _{GS} = - 10 V, I _D = - 17 A		0.020			
	D	V _{GS} = - 10 V, I _D = - 40 A, T _J = 125 °C		0.030		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 40 A, T _J = 150 °C		0.035			
		V _{GS} = - 4.5 V, I _D = - 14 A		0.025			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 17 A		61		S	
Dynamic ^b	•						
Input Capacitance	C _{iss}			2950			
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		380		pF	
Reverse Transfer Capacitance	C _{rss}			305			
Total Gate Charge ^c	Q_g			110	165		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -40 \text{ A}$		19		nC	
Gate-Drain Charge ^c	Q_{gd}]		28			
Turn-On Delay Time ^c	t _{d(on)}			15	23		
Rise Time ^c	t _r	$V_{DD} = -30 \text{ V}, R_{L} = 0.6 \Omega$		70	105		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -40 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 6$		175	260	ns	
Fall Time ^c	t _f	Ω		175	260		
Source-Drain Diode Ratings and Cha	aracteristics -	T _C = 25 °C ^b					
Continuous Current	IS				- 40	٨	
Pulsed Current	I _{SM}				- 80	Α	
Forward Voltage ^a	V _{SD}	I _F = - 40 A, V _{GS} = 0 V		- 1	- 1.6	V	
Reverse Recovery Time	t _{rr}	I _F = - 40 A, dI/dt = 100 A/μs		45	70	ns	

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

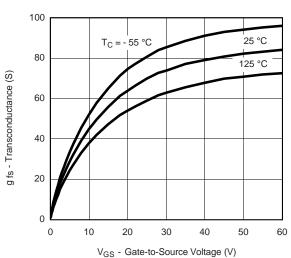
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



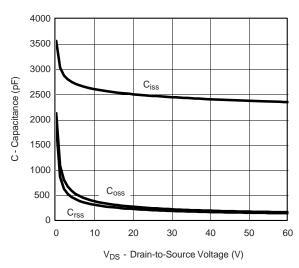
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



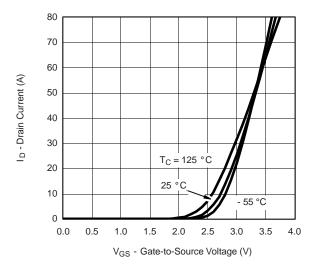
Output Characteristics



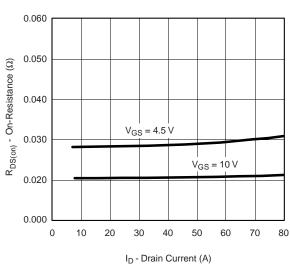
Transconductance



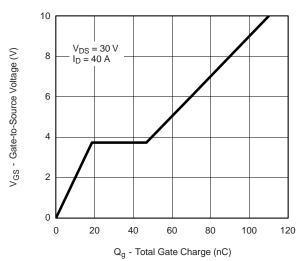
Capacitance



Transfer Characteristics



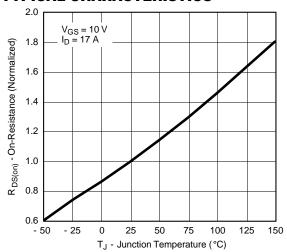
On-Resistance vs. Drain Current



Gate Charge

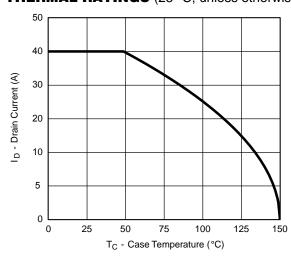


TYPICAL CHARACTERISTICS

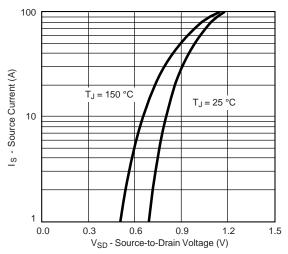


On-Resistance vs. Junction Temperature

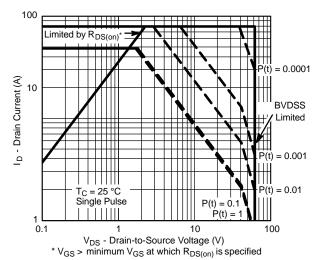
THERMAL RATINGS (25 °C, unless otherwise noted)



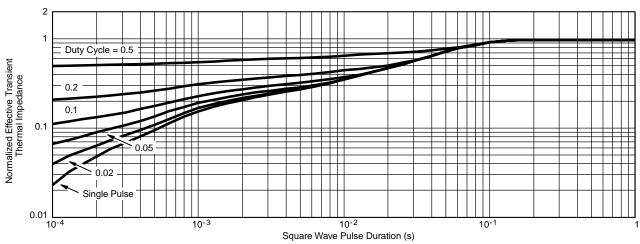
Drain Current vs. Case Temperature



Source-Drain Diode Forward Voltage



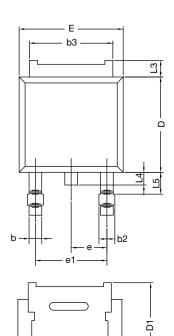
Safe Operating Area



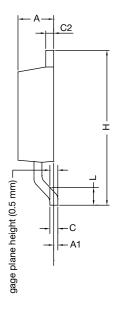
Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA CASE OUTLINE



E1



	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
С	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	5.21	-	0.205	-
Е	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
Н	9.40	10.41	0.370	0.410
е	2.28 BSC		0.090	BSC
e1	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.14	1.52	0.045	0.060
ECN: X12-0247-Rev. M, 24-Dec-12				

ECN: X12-0247-Rev. M, 24-Dec-1: DWG: 5347

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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